Amendments to the claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Currently Amended) A method comprising:

forming a flexible, non- electrically conductive membrane with holes, the membrane for a land grid array ~~direct socket loading device~~; and

attaching the membrane to the ~~direct socket loading device~~ land grid array, the holes positioned to permit electrical contact between the land grid array and an IC device.

2. – 8. (Canceled)

9. (Currently Amended) The method of claim [[2]] 1 wherein the ~~membrane is attached to a frame, the frame formed to connect to a socket of the land grid array~~ method comprises:

attaching the membrane to a frame;

connecting the frame to a socket of the land grid array.

10. – 29 (Canceled)

30. (New) The method of claim 9 wherein the frame is made of molded plastic.

31. (New) The method of claim 9 wherein the connecting of the frame to the socket is performed by snapping the frame on to the socket.

32. (New) The method of claim 9 wherein the membrane is made of a synthetic polymeric resin.

33. (New) The method of claim 9 wherein the attaching of the membrane to the frame is performed by stretching the membrane across the frame.

34. (New) The method of claim 33 wherein the membrane is cut to fit the frame prior to the attaching.

35. (New) A method, comprising:

forming a flexible, non-electrically conductive membrane with holes;

cutting the membrane for attachment to a frame;

attaching the membrane to the frame; and,

attaching the frame to a land grid array socket, the holes of the membrane within the frame being aligned with corresponding electrical contacts of the land grid array socket so as to permit electrical connection of the land grid array electrical contacts to an IC device through the holes.

36. (New) The method of claim 35 wherein the attaching of the membrane to the frame is performed by stretching the membrane across the frame.

37. (New) The method of claim 36 wherein the attaching of the frame to the land grid array socket is performed by snapping the frame into the socket.

38. (New) The method of claim 37 wherein the membrane is made of a synthetic polymeric resin.

39. (New) A method comprising:

forming a flexible, non- electrically conductive membrane incorporated with electrically conductive pads, the membrane for a land grid array; and

attaching the membrane to the land grid array, the electrically conductive pads positioned to permit electrical contact between the land grid array and an IC device.

40. (New) The method of claim 39 wherein the membrane comprises polyimide and the pads incorporated within the membrane are formed by flexible circuit technology.

41. (New) The method of claim 40 wherein one of the pads is created by laminating a flexible polymer film to a sheet of conductive metal.

42. (New) The method of claim 39 wherein the method comprises:

attaching the membrane to a frame;

connecting the frame to a socket of the land grid array.

43. (New) The method of claim 42 wherein the frame is made of molded plastic.

44. (New) The method of claim 42 wherein the connecting of the frame to the socket is performed by snapping the frame on to the socket.

45. (New) The method of claim 42 wherein the membrane is made of a synthetic polymeric resin.

46. (New) The method of claim 42 wherein the attaching of the membrane to the frame is performed by stretching the membrane across the frame.

47. (New) The method of claim 46 wherein the membrane is cut to fit the frame prior to the attaching.

48. (New) A method, comprising:

forming a flexible, non-electrically conductive membrane having a plurality of electrically conductive pads on both sides of said membrane, wherein, those of said pads that are vertically aligned through said membrane are electrically connected to one another by a respective via through said membrane;

cutting the membrane for attachment to a frame;

attaching the membrane to the frame; and,

attaching the frame to a land grid array socket, wherein the pairs of electrically connected pads of the membrane within the frame are aligned with corresponding electrical contacts of the land grid array socket so as to permit electrical connection of the land grid array electrical contacts to an IC device through the pairs of electrically connected pads.

49. (New) The method of claim 48 wherein the attaching of the membrane to the frame is performed by stretching the membrane across the frame.

50. (New) The method of claim 49 wherein the attaching of the frame to the land grid array socket is performed by snapping the frame into the socket.

51. (New) The method of claim 50 wherein one of the pads is created by laminating a flexible polymer film to a sheet of conductive metal.